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RF2369

3V LOW NOISE AMPLIFIER/ 3V PA DRIVER AMPLIFIER

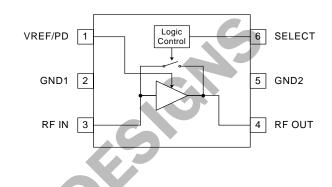
RoHS Compliant & Pb-Free Product
Package Style: SOT 6-Lead

Features

- Low Noise and High Intercept Point
- Adjustable Bias Current
- LNA Bypass Loss is +2dB
- 150 MHz to 2500 MHz Operation
- Meets IMD Tests with Two Gain States/Single Logic Control Line

Applications

- CDMA/Cellular Bypass LNA
- CDMA/Cellular Bypass Driver Amplifier
- General Purpose Amplification
- Commercial and Consumer Systems



Functional Block Diagram

Product Description

The RF2369 is a switchable low noise amplifier with a very high dynamic range designed for digital cellular applications. The device functions as an outstanding front end low noise amplifier. When used as an LNA, the bias current can be set externally. When used as a PA driver, the IC can operate directly from a single cell Li-ion battery and includes a power down feature that can be used to completely turn off the device. The IC is featured in a standard SOT 6-lead plastic package.

Ordering Information

RF2369 3V Low Noise Amplifier/ 3V PA Driver Amplifier RF2369PCBA-41X Fully Assembled Evaluation Board (LNA)

Optimum Technology Matching® Applied

☑ GaAs HBT	☐ SiGe BiCMOS	☐ GaAs pHEMT	☐ GaN HEMT
☐ GaAs MESFET	☐ Si BiCMOS	☐ Si CMOS	
☐ InGaP HBT	☐ SiGe HBT	☐ Si BJT	

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RF2369



Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage	-0.5 to +8.0	V _{DC}
Input RF Level	+10	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

RoHS status based on EUDirective 2002/95/EC (at time of this document revision).

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Davamatav	Specification		Unit	Condition	
Parameter	Min.	Тур.	Max.	Unit	Condition
Overall					T _{AMB} =25°C, V _{CC} =3.0V
Frequency Range	150	824 to 894	2500	MHz	
Cellular Low Noise Amplifier					
Frequency	869		894	MHz	
HIGH GAIN MODE					Gain Select < 0.8 V, V _{PD} /V _{REF} =3 V
Gain	14.0	15.5	17.0	dB	
Noise Figure		1.6	2.0	dB	
Input IP3	9.0	11.5		dBm	
Input VSWR			2:1		
Output VSWR			2:1		
Current Drain		7.5	10.0	mA	
BYPASS MODE					Gain Select > 1.8 V, V _{PD} /V _{REF} = 0 V
Gain	-3	-2	-1	dB	
Input IP3	+10	+24		dBm	
Input VSWR			2:1		
Output VSWR			2:1		
Current Drain		2.0	4.0	mA	
Cellular CDMA Driver					
Frequency	824		849	MHz	
HIGH GAIN MODE					Gain Select < 0.8 V, V _{PD} /V _{REF} = 3 V
Gain	14.0	15.5	17.0	dB	
Noise Figure		2.0	2.5	dB	
Output Power	4			dBm	
ACPR1		-65		dBc/30kHz	P _{OUT} =+4dBm, <u>+</u> 885kHz offset
ACPR2		-70		dBc/30kHz	P _{OUT} =+4dBm, <u>+</u> 1.98MHz offset
Input VSWR			2:1		
Output VSWR			2:1		
Current Drain		8.5		mA	
BYPASS MODE					Gain Select > 1.8 V, V _{PD} /V _{REF} =0 V
Gain	-3.0	-2.0	-1.0	dB	
Input IP3	+10	+24		dBm	
Input VSWR			2:1		
Output VSWR			2:1		
Current Drain		2.0	4.0	mA	



Parameter	Specification		Unit	Condition		
raidilielei	Min.	Тур.	Max.	Ullit	Condition	
Power Supply						
Voltage (V _{CC})		3		V		
V _{SELECT} Low			0.8	V	High Gain mode. Select<0.8V, V _{PD} /V _{REF} =3V	
V _{SELECT} High	1.8			V	Low Gain mode. Select>1.8V, V _{PD} /V _{REF} =0V	
Power Down	0		10	μΑ	Gain Select < 0.8 V, V _{PD} /V _{REF} = 0 V, V _{CC} = 0 V	

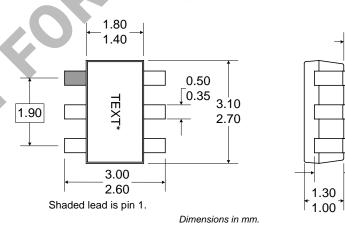
Bypass Possibility

Gain Select	V_{PD}/V_{REF}	V _{cc}	Current	Comments
>1.8V	OV	3V	2.3 mA	Recommended Bypass Mode
>1.8V	3V	3V	3.4 mA	Alternative Bypass Mode



Pin	Function	Description	Interface Schematic
1	VREF/PD	For low noise amplifier applications, this pin is used to control the bias current. An external resistor can be used to set the bias current for any V_{PD} voltage.	VREF/PD
2	GND1	Ground connection. For best performance, keep traces physically short and connect immediately to ground plane.	
3	RF IN	RF input pin.	To Bias Circuit RF IN ORF OUT
4	RF OUT	Amplifier output pin. This pin is an open-collector output. It must be biased to V_{CC} through a choke or matching inductor. This pin is typically matched to 50Ω with a shunt bias/matching inductor and series blocking/matching capacitor. Refer to application schematics.	
5	GND2	LNA emittance inductance. Total inductance is comprised of package+bondwire+stripline (L1) on PCB.	
6	SELECT	This pin selects high gain and bypass. Select ≤ 0.8V, high gain. Select ≥ 1.8V, low gain.	

Package Drawing



*When Pin 1 is in upper left, text reads downward (as shown).

0.10

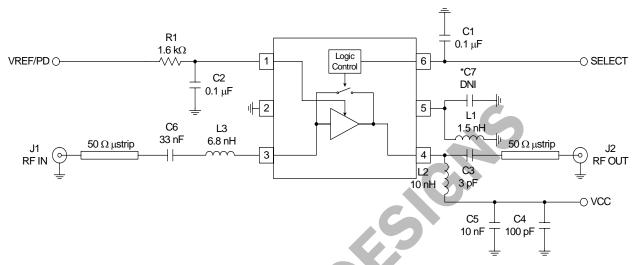
MAX.

0.90

0.70

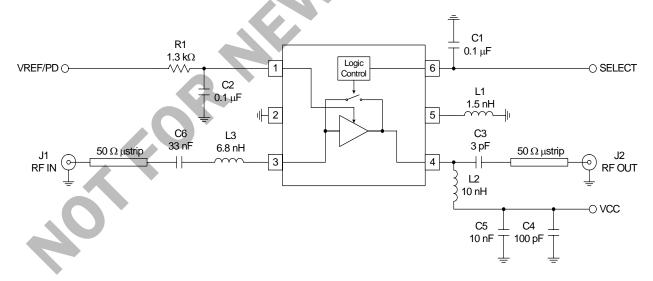


Application Schematic Cellular Low Noise Amplifier ~881MHz



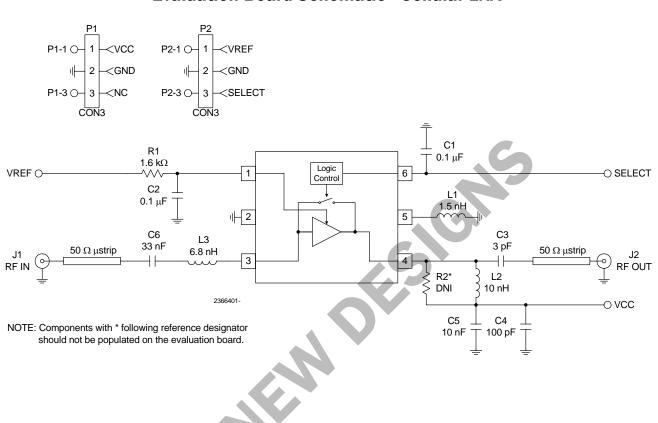
* It is recommended added to initial customer PCBA layout for flexibility to optimize performance.

Application Schematic Cellular Driver Amplifier ~836 MHz





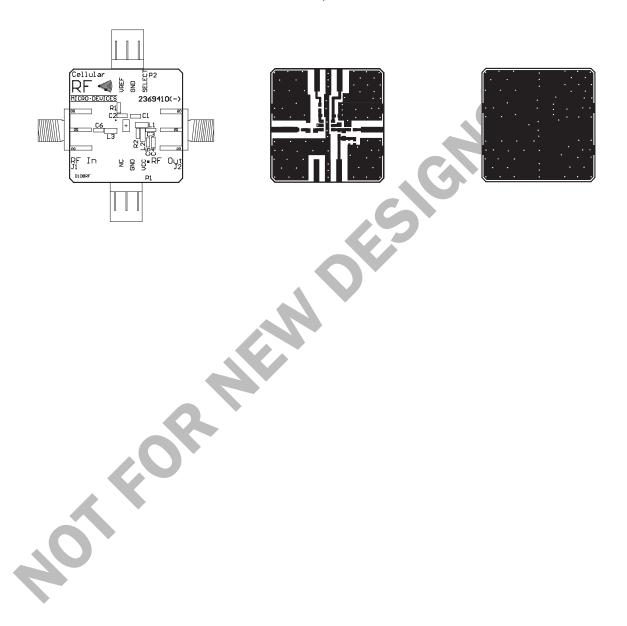
Evaluation Board Schematic - Cellular LNA





Evaluation Board Layout Board Size 1.0" x 1.0"

Board Thickness 0.032", Board Material FR-4



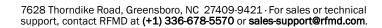


RoHS* Banned Material Content

RoHS Compliant: Yes
Package total weight in grams (g 0.013
Compliance Date Code: 435
Bill of Materials Revision: Rev: B
Pb Free Category: e3

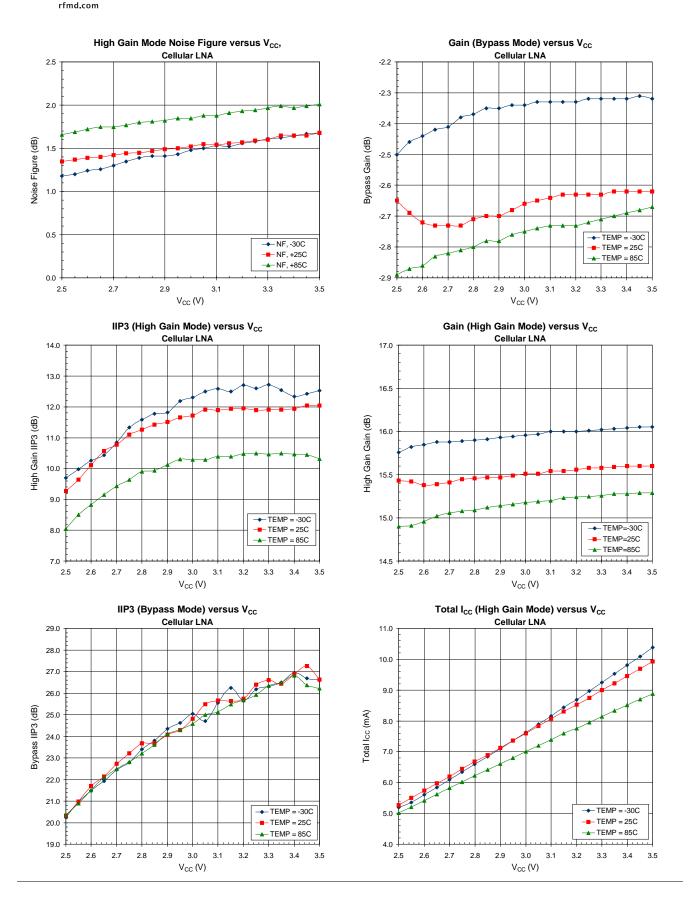
Bill of Materials	Parts Per Million (PPM)					
	Pb	Cd	Hg	Cr VI	PBB	PBDE
Die	0	0	0	0	0	0
Molding Compound	0	0	0	0	0	0
Lead Frame	0	0	0	0	0	0
Die Attach Epoxy	0	0	0	0	0	0
Wire	0	0	0	0	0	0
Solder Plating	0	0	0	0	0	0

This RoHS banned material content declaration was prepared solely on information, including analytical data, provided to RFMD by its suppliers, and applies to the Bill of Materials (BOM) revision noted above.



^{*} DIRECTIVE 2002/95/EC OF THE EUROPEAN PARLIAMENT AND OF THE COUNCIL of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment





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